

Amendments to the Specification:

Please replace the paragraph beginning on Page 8, line 7 with the following amended paragraph:

Figures 2 and 3 illustrate a wear ring which is in accordance with an embodiment of the present invention. As shown, the wear ring 20 is configured to hold a semiconductor wafer 22 and is configured to be pressed to a polishing pad 24 on a polishing table 26. The wear ring 20 includes an inlet 28 which is in communication with at least one channel or distribution loop 30 in the wear ring 20. A plurality of outlets 32 are in communication with the channel 30. The wear ring 20 is configured such that slurry is injectable (the injection of slurry is represented by arrow 34 in Figures 2 and 3) into the at least one channel 30 such that the slurry exits the outlets 32 in the wear ring 20 and contacts the polishing pad 24 on the polishing table 26. Preferably, the wear ring 20 is pressed against the polishing pad 24, and both the polishing table 26 and wear ring 20 are rotated (as represented by arrows [34] 36 in Figure 2).

Please replace the paragraph beginning on Page 9, line 1 with the following amended paragraph:

While Figures 2 and 3 illustrate one embodiment of the wear ring [12] 20, other embodiments are entirely possible. For example, while Figures 2 and 3 depict the channel 30 being within the wear ring [12] 20, the channel 30 can instead be provided as being formed in the underside of the wear ring [12] 20 so that the slurry can flow into the channel and have full contact with the pad 24. Also, while the channel 30 and outlets 32 are shown centered in Figures 2 and 3, the channel 30 and outlets 32 can instead be provided nearer the wafer.